



## Material Content Data Sheet



Sales Product Name	SAK-XC2768X-136F128L AA			Issued		29. August 2013		
MA#	MA001025854							
Package	PG-LQFP-100-8			Weight*		759.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	56.102	7.38	7.38	73834	73834
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		90	
	non noble metal	zinc	7440-66-6	0.275	0.04		362	
	non noble metal	iron	7439-89-6	5.501	0.72		7239	
	non noble metal	copper	7440-50-8	223.351	29.39	30.16	293944	301635
wire	noble metal	gold	7440-57-5	3.402	0.45	0.45	4477	4477
encapsulation	organic material	carbon black	1333-86-4	2.234	0.29		2940	
	plastics	epoxy resin	-	60.324	7.94		79390	
	inorganic material	silicondioxide	60676-86-0	384.287	50.58	58.81	505747	588077
leadfinish	non noble metal	tin	7440-31-5	9.288	1.22	1.22	12224	12224
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3284	3284
glue	plastics	epoxy resin	-	3.128	0.41		4117	
	noble metal	silver	7440-22-4	9.385	1.24	1.65	12352	16469
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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